FORM PTO-1449 (Modified)
U.S. Department of Commerce, Patent and Trademark Office

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Use several sheets if necessary)

Docket No.	Serial No.
02-5624	10/676,934
Applicants: Byung-Sung Kwak et al.	
Filing Date Herewith	Group 2823 ~~Unknown~~

U.S. Patent Documents

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
TWP	AA	5,874,367	2/23/99	Dobson	~~438~~	~~787~~	
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

Foreign Patent Documents

		Document Number	Date	Country	Class	Subclass	Translation Yes	Translation No
	AL							
	AM							
	AN							
	AO							
	AP							

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

TWP	AR	Bothra, S., et al., "Integration of 0.25 μm Three and Five Level Interconnect System for High Performance ASIC", 1997 Proceedings Fourteenth International VMIC Conference, Santa Clara, CA, June 10-12, 1997, pp.43-48.
TWP	AS	Brongersma, S.H., et al., 'Non-Correlated Behavior of Sheet Resistance and Stress During Self-Annealing of Electroplated Copper", IITC, 1999, pp.290-292.
TWP	AT	Dobson, C.D., et al., "Advanced SiO_2 Planarization Using Silane and H_2O_2", Semiconductor International, December 1994, pp. 85-88.

Examiner [signature] Date Considered 9/27/04

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance *and* not considered. Include copy of this form with your communication to applicant.

FORM PTO-1449 (Modified) U.S. Department of Commerce, Patent and Trademark Office	Docket No. 02-5624	Serial No. 10/676,937
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	Applicants Byung-Sung Kwak et al.	
	Filing Date Herewith	Group Unknown 2823

U.S. Patent Documents

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	BA						
	BB						
	BC						
	BD						
	BE						
	BF						
	BG						
	BH						
	BI						
	BJ						
	BK						

Foreign Patent Documents

		Document Number	Date	Country	Class	Subclass	Translation Yes	Translation No
	BL							
	BM							
	BN							
	BO							
	BP							

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

TVP	BR	Hau-Riege, Stefan P., Handbook entitled "Copper Interconnect Technology", University of California-Berkeley Extension Course, April, 2002, pp. 129-137.
TVP	BS	Kittel, Charles, Introduction to Solid State Physics, 6th ed., New York: John Wiley & Sons, 1986, pp. 143, 145.
TVP	BT	McClatchie, S., et al., "Low Dielectric Constant Oxide Films Deposited Using CVD Techniques", 1998 Proceedings Fourth International DUMIC Conference, February 16-17, 1998, pp. 311-318.

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	CA						
	CB						
	CC						
	CD						
	CE						
	CF						
	CG						
	CH						
	CI						
	CJ						
	CK						

Foreign Patent Documents

		Document Number	Date	Country	Class	Subclass	Translation Yes	Translation No
	CL							
	CM							
	CN							
	CO							
	CP							

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

TVP	CR	Peters, Laura, "Low-k Dielectrics: Will Spin-On or CVD Prevail?", Semiconductor International, Vol. 23, No. 6, June, 2000, pp. 108-110, 114, 116, 118, 122, and 124.
TVP	CS	Peters, Laura, "Pursuing the Perfect Low-k Dielectric", Semiconductor International, Vol. 21, No. 10, September, 1998, pp. 64-66, 68, 70, 72, and 74.
TVP	CT	Ramanan, V.R.V., et al., "Crystallization Kinetics in Fe-B-Si Metallic Glasses", J. Appl. Phys., Vol. 53, No. 3, March, 1982, pp. 2273-2275.

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	DA						
	DB						
	DC						
	DD						
	DE						
	DF						
	DG						
	DH						
	DI						
	DJ						
	DK						

Foreign Patent Documents

		Document Number	Date	Country	Class	Subclass	Translation Yes	Translation No
	DL							
	DM							
	DN							
	DO							
	DP							

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

TWP	DR	Ritzdorf, T., et al., "Comparative Investigation of Plating Conditions on Self-Annealing of Electrochemically Deposited Copper Films", IITC, 1999, pp. 287-289.
TWP	DS	Rossnagel, S.M., et al., "From PVD to CVD to ALD for Interconnects and Related Applications", IITC, 2001, p. 2.
	DT	

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[signature]	9/27/04

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